

NOTES, UNLESS OTHERWISE SPECIFIED:

1. The netname "V5P0V" represents connection to the +5.0V power buss.
2. The netname "V3P3V" represents connection to the +3.3V power buss
3. The netname "V2P5VREF" represents connection to the +2.5V reference buss
4. The netname "V2P5VREFBUF" represents connection to the +2.5V buffered reference buss.
5. The netname "GND" represents connection to the ground plane.
6. A "Z" suffix on a signal name indicates an active low signal.
7. All components with designators "U\*", "Q\*", and "D\*" are electrostatic discharge sensitive.
8. All resistor values are in ohms.
9. All capacitor values in microfarads unless otherwise specified.



COMPUTER GENERATED DRAWING - DO NOT REVISE MANUALLY

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
-	Draft Release	04/16/2014	HPC
A	ECO 2141379: REV A Release		

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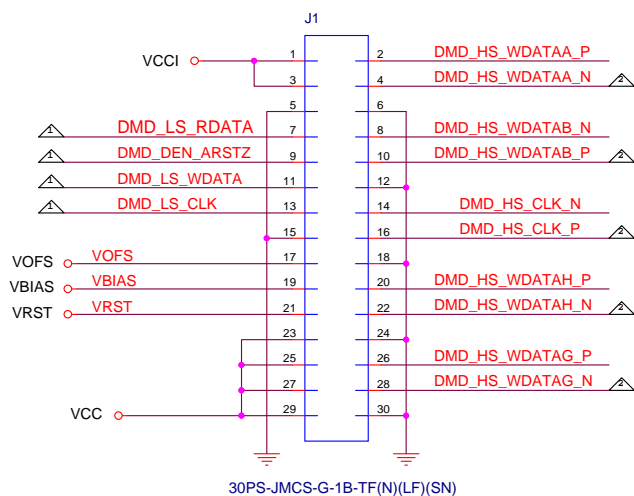
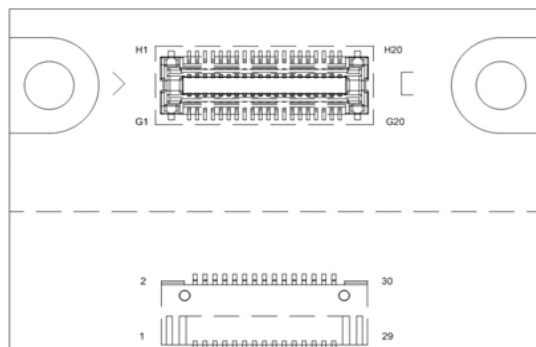
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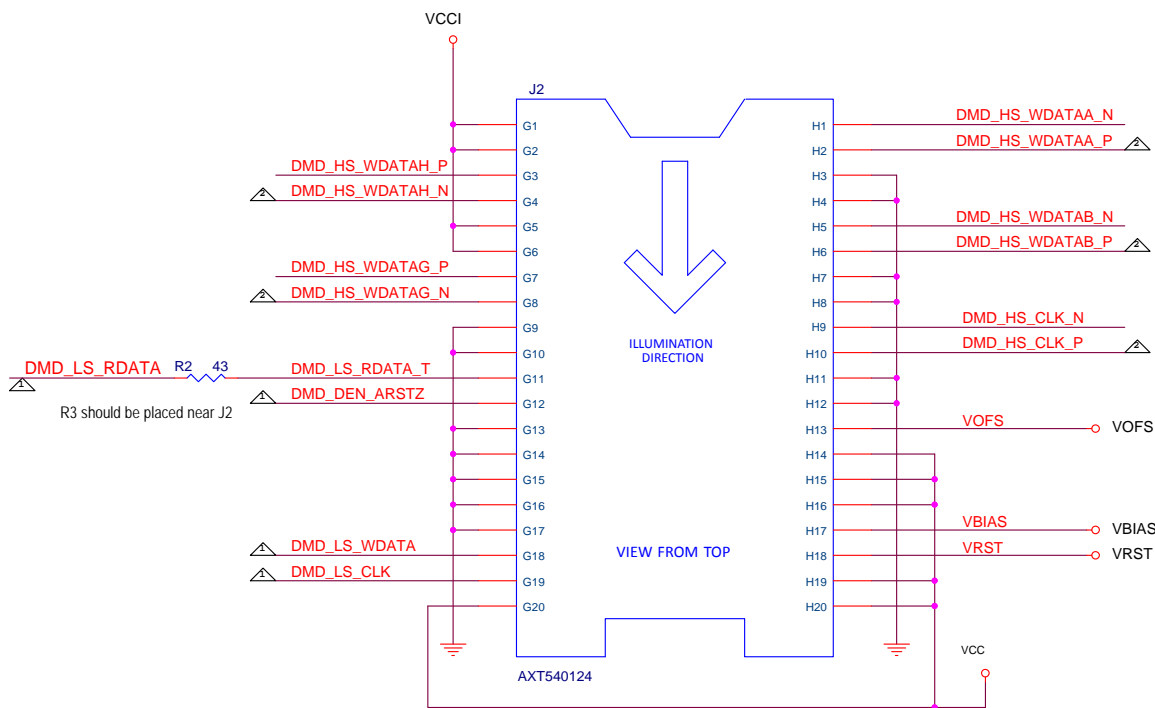
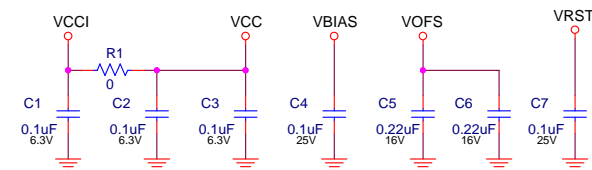
Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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		ENGR	04/16/2014		
		APVD			
		MFG			
		QA		TITLE <b>ESD, Mobile Spectroscopy DMD Board</b>	
	0314CP				
NEXT ASSY	USED ON			<b>A3</b>	DRAWING NO <b>2514016</b>
APPLICATION		SW	Allegro Design Entry 16.6		
				SCALE	SHEET 1 of 3
					REV A

# Connector side silkscreen information



△ = 68 ohm = +/- 6.8 ohms Single Ended Signal  
 △△ = 100 ohm = +/- 10 ohms Differential Signal



Revision History

Rev. -- : Draft Release ~ 04/16/2014

Rev. A: ECO 2141379 ~ 04/??/2014

Schematic Revision History

TEXAS INSTRUMENTS	DWN	DATE	A3	DRAWING NO	2514016	REV	A
	04/16/2014						
	ISSUE DATE		SCALE		SHEET 3 OF 3		